

**REMARKS**

This paper responds to the Office Action mailed on June 8, 2006.

No claims are amended, canceled, or added; as a result, claims 62, 64-82, and 84-87 remain pending in this application.

**Objection to the Drawings**

The Office Action indicates that the feature of claim 62 whereby “the inhibiting layer is **embedded** in the second conductive layer”, and the feature recited in claims 64, 66, and 74 whereby the diffusion barrier layer is formed “over the inhibiting layer **and** the second conductive layer” must be shown in the drawings.

Applicant submits that the drawings show the features recited in claims 62 whereby “the inhibiting layer is **embedded** in the second conductive layer”. For example, FIG. 1 shows inhibiting layer 130 and second conductive layer 128. The specification, page 8, lines 22-23, describes that in an embodiment, the inhibiting layer 130 includes a layer that is **embedded** in the electrode 128. For another example, FIG. 3F shows inhibiting layer 330 and second conductive layer 328. The specification, page 13, lines 14-15, describes that in an embodiment, inhibiting layer 330 is **embedded** in conductive layer 328. Thus, the drawings show the feature of claim 62 whereby “the inhibiting layer is **embedded** in the second conductive layer”.

Applicant also submits that the drawings show the feature recited in claims 64, 66, and 74 whereby the diffusion barrier layer is formed “over the inhibiting layer **and** the second conductive layer”. For example, FIG. 3H shows inhibiting layer 330 **and** conductive layer 328. FIG. 3L shows a layer 360 over inhibiting layer 330 and conductive layer 328. The specification, page 15, line 3, describes that layer 360 may be considered a diffusion barrier layer. Therefore, the drawings show the feature recited in claims 64, 66, and 74 whereby the diffusion barrier layer is formed “over the inhibiting layer **and** the second conductive layer”.

Based on the discussion above, Applicant submits that the drawings show the feature of claim 62 whereby “the inhibiting layer is **embedded** in the second conductive layer”, and the feature recited in claims 64, 66, and 74 whereby the diffusion barrier layer is formed “over the inhibiting layer **and** the second conductive layer”. Accordingly, Applicant requests reconsideration and withdrawal of the objection to the drawings.

### CONCLUSION

Applicant respectfully submits that the claims are in condition for allowance, and notification to that effect is earnestly requested. The Examiner is invited to telephone Applicant's attorney at (612) 373-6969 to facilitate prosecution of this application.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

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By his Representatives,

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Date 8 August 2006

By   
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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop Amendment, Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this 8 day of August 2006.

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